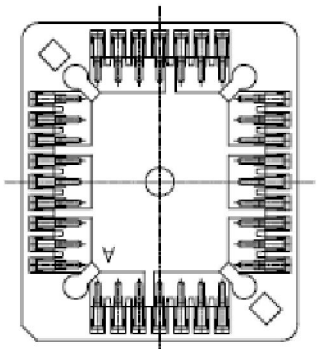
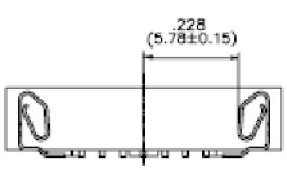
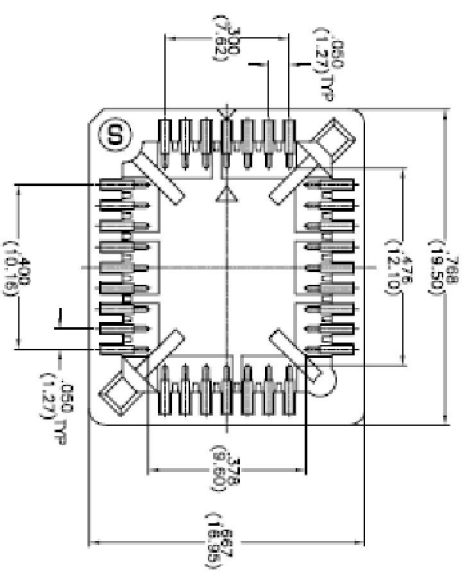
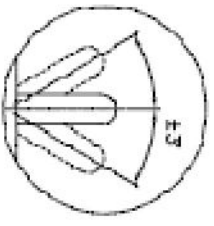
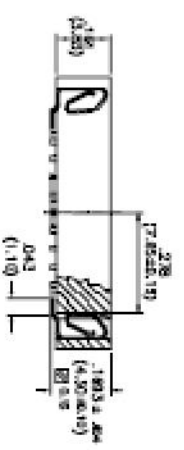
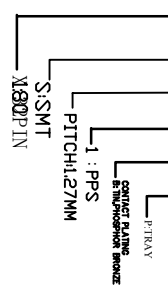


REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	CHANGER
A				06-4-13	

Ordering information
T-D P C 32 S E 1 B P-00



底视图



左右偏許公差為3°

SPECIFICATIONS
 INSULATION RESISTANCE:
 1000 MEGOHMS MIN.
 DIELECTRIC WITHSTAND STRENGTH:
 500V (r.m.s) AC FOR 1 MINUTE.
 CONTACT RESISTANCE:
 30 mΩ MAX.
 TEMPERATURE:
 -55°C ~ +105°C.

MATERIALS AND FINISH
 HOUSING MATERIAL:
 POLYPHENYLENE SULFIDE
 UL-94V-0.
 CONTACTS:
 PHOSPHOR BRONZE.
 PLATING:
 150μ" MIN SN
 50μ" MIN NICKEL OVERALL.



得升電子股份有限公司
DISMT MECHANICAL ELECTRONIC CO., LTD

TOLERANCE UNSPECIFIED: X ±0.50 X.X ±0.25 X.XX ±0.15 X.XXX ±0.05 X' ±2' X.X' ±1'	PROJECTION: 	UNIT: mm [inch]	SCALE: 1:1	SIZE: A4
DRAWN BY: 杨熊	CHECKED BY: 何智权	DATE: 6-4-13	DATE: 6-4-13	DATE: 6-4-13
APPROVED BY: 陈宗渊				
TITLE: 成品规格图	PART NAME: SMD TYPE 32 POS 4.3MM	PART NO. T-DPC32SF1BR-00	MOLD NO.	DRAW NO. T-DPC32SF1BR-00
				SHEET 1 OF 1